



# SCALE 1:1

0.20 С

NOTE 5 B

## **SOIC8 MISSING PIN 3** CASE 751EV **ISSUE O**

**DETAIL A** 

DETAIL A

**DATE 19 SEP 2017** 

#### NOTES:

NOTE 6

C SEATING PLANE

Α1

**END VIEW** 

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10mm IN EXCESS OF MAXIMUM MATERIAL 3.
- 4. DIMENSIONS D & E1 DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM F.
  DATUMS A AND B ARE TO BE DETERMINED AT
- DATUM F.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS		
DIM	MIN	MAX	
Α	1.35	1.75	
A1	0.10	0.25	
b	0.33	0.51	
С	0.19	0.25	
D	4.80	5.00	
E	5.80	6.20	
E1	3.80	4.00	
е	1.27 BSC		
Ĺ	0.40	1.27	
L2	0.25 BSC		
M	O٥	8 °	

## RECOMMENDED SOLDERING FOOTPRINT\*

NOTE 5

**E1** 

7X b

**TOP VIEW** 

SIDE VIEW

0.10 C

⊕ 0.12 M C A-B D

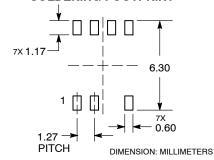
□ 0.10 | C | A-B |

0.10  $\triangle$ 

C SEATING PLANE

С

L2



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code

= Assembly Location Α

L = Wafer Lot Υ = Year = Work Week W = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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